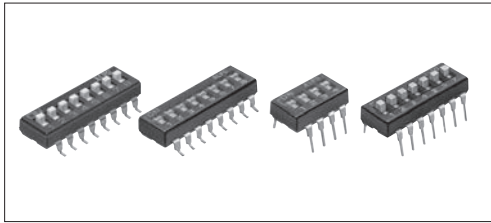


Highly reliable IC-size type with gold contact supports automatic insertion.



Typical Specifications

Items		Specifications
Rating (max.) / (min.) (Resistive load)		25mA 24V DC (At opening and closing) 0.1A 50V DC (When energized) / 10 μ A 1V DC
Contact resistance (Initial performance / After lifetime)		50m Ω max. / 100m Ω max.
Operating force		3.5 \pm 2.5N
Operating life	Without load	3,000cycles
	With load	3,000cycles (25mA 24V DC)

Detector

Slide

Push

Rotary

Encoders

Power

Dual-in-line
Package Type

TACT Switch™

Product Line

Soldering	Actuator configuration	Packaging style	Poles	Minimum order unit (pcs.)		Product No.	Drawing No.	
				Japan	Export			
Insertion	Standard	Stick	2	70	7,000	SSGM120100	1	
			3	52	5,200	SSGM130100		
			4	40	4,000	SSGM140100		
			5	33	3,300	SSGM150100		
			6	28	2,800	SSGM160100		
			7	25	2,500	SSGM170100		
			8	22	2,200	SSGM180100		
			9	19	1,900	SSGM190100		
			10	18	1,800	SSGM1A0100		
			Flat			4		40
	6	28				2,800	SSGM260100	
	8	22				2,200	SSGM280100	
	10	18				1,800	SSGM2A0100	
	Reflow	Standard	Taping	4	800	3,200	SSGM640200	3
8				1,600		SSGM680200		
Flat		2		1,000	4,000	SSGM720101	4	
		4				SSGM740101		
		6				SSGM760102		
		8			2,000	SSGM780103		

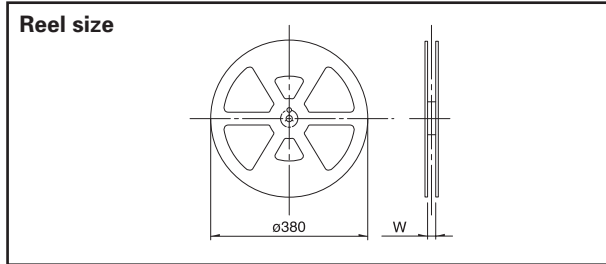
Note

Other varieties are also available. Please inquire.

Packing Specifications

Taping

Unit:mm



Product No.	Number of packages (pcs.)			Reel width W (mm)	Tape width (mm)	Export package measurements (mm)
	1 reel	1 case / Japan	1 case/ export packing			
SSGM640200	800	1,600	3,200	25.4	24	406 × 406 × 190
SSGM680200		800	1,600	45.4	44	
SSGM720101 SSGM740101	1,000	2,000	4,000	25.4	24	
SSGM760102		1,000	2,000	33.4	32	
SSGM780103				45.4	44	

Stick

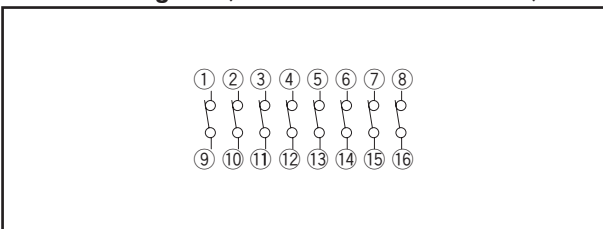
Product No.	Number of packages (pcs.)			Export package measurements (mm)
	1 stick	1 case / Japan	1 case / export packing	
SSGM120100	70	1,400	7,000	578 × 180 × 202
SSGM130100	52	1,040	5,200	
SSGM140100 SSGM240100	40	800	4,000	
SSGM150100	33	660	3,300	
SSGM160100 SSGM260100	28	560	2,800	
SSGM170100	25	500	2,500	
SSGM180100 SSGM280100	22	440	2,200	
SSGM190100	19	380	1,900	
SSGM1A0100 SSGM2A0100	18	360	1,800	

Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from direction A)
1	<p>Standard</p>	
2	<p>Flat</p>	
3	<p>Standard</p>	
4	<p>Flat</p>	

Circuit Diagram (Viewed from Direction A)



Number of Poles and Outline Dimension (L)

Number of poles(N)	2	3	4	5	6	7	8	9	10
L (mm)	6.9	9.4	11.9	14.5	17	19.6	22.1	24.6	27.2

Detector

Slide

Push

Rotary

Encoders

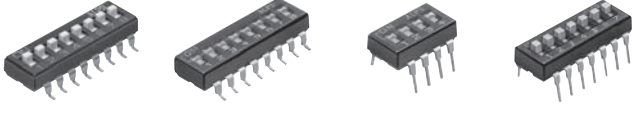

Power

Dual-in-line Package Type

TACT Switch™

Dual In-line Package Type Switches

List of Varieties

Series		SSGM	
Photo			
Operating temperature range		-40°C to +85°C	
Automotive use		●	
Life cycle			
Rating (max.) / (min.) (Resistive load)		25mA 24V DC (At opening and closing), 0.1A 50V DC (When energized), 10 μA 1V DC	
Durability	Operating life	Without load	3,000cycles
		With load	3,000cycles (25mA 24V DC)
Electrical performance	Contact resistance (Initial performance / After life time)		50mΩ max. / 100mΩ max.
	Insulation resistance		100MΩ min. 500V DC
	Voltage proof		500V AC for 1minute
Mechanical performance	Terminal strength		5N for 1minute
	Actuator strength	Operating direction	10N
		Pulling direction	10N
Environmental performance	Cold		-40±2°C for 250h
	Dry heat		85±2°C for 250h
	Damp heat		60±2°C, 90 to 95%RH for 250h
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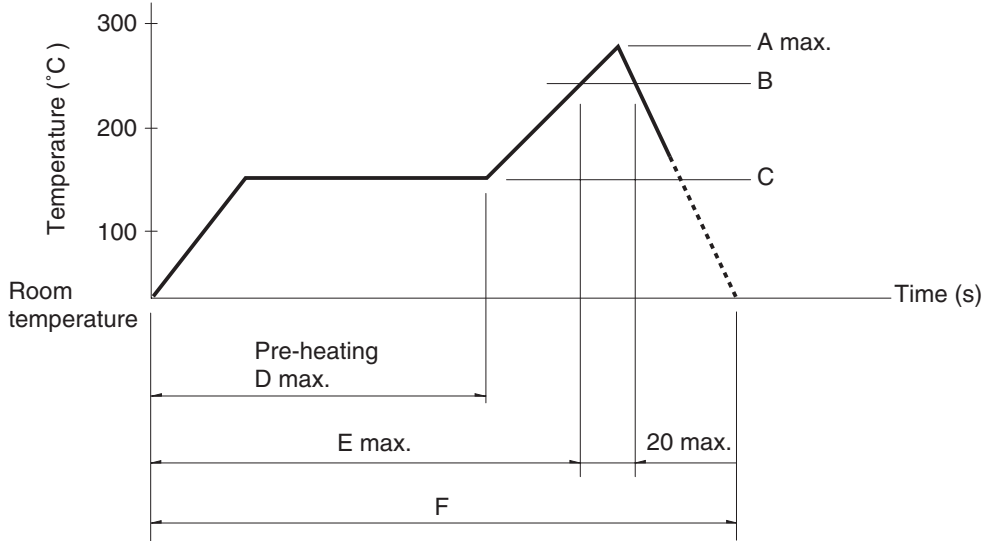
Note

● indicates applicability to all products in the series.

Dual In-line Package Type Switches Soldering Conditions

Example of Reflow Soldering Condition

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 φ CA (K) or CC (T) at soldering portion (copper foil surface).
A heat resisting tape should be used for fixed measurement.
3. Temperature profile



Series (Reflow type)	A (°C) 3s max.	B (°C)	C (°C)	D (s)	E (s)	F (s)
SSGM	250	240	150	180	————	————

Notes

1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering Condition

Soldering temperature	Soldering time
350±5°C	5s max.

Reference for Dip Soldering Condition

(For insertion terminal types)

Items		Dip soldering	
Preheating temperature	Preheating time	Soldering temperature	Duration of immersion
120°C max.	90s max.	270±5°C	10±1s max.